

Amendments to the Specification are as follows:

Please amend the second paragraph on page 15 as follows:

(Amended) The intermediate radiating layer 11 is formed in the rear of the upper shield layer 9 without making contact with the upper shield layer 9 and a conductive connecting portion 40(not shown). When the intermediate radiating layer 11 is separated from the upper shield layer 9, heat of the intermediate radiating layer 11 is less transmitted to the upper shield layer 9, thereby decreasing the effect of a temperature rise of the upper shield layer 9 on the magnetoresistive element 6.

Please amend the third paragraph on page 20 as follows:

(Amended) The second coil 23 has a region facing the lower core layer 13 and a region facing the upper radiating layer 15. Like in the first coil 21, in the second coil 23, the upper radiating layer 15 preferably faces the upper radiating layer 15 over substantially the whole region behind the region facing the lower core layer 13.

Please amend the first paragraph on page 29 as follows:

(Amended) The method of manufacturing the thin film magnetic head of the second embodiment comprises removing the insulating layer 5 from the top of the lower radiating layer 4, and then forming the second connecting portion 28 by plating a metal film of Cu, AiAu, or the like. After the second connecting portion 28 is formed, the intermediate radiating layer 26 is formed by plating a permalloy film.